| | Hits | Search Text | DBs |
|---|---|---|---|
| 29 | 3 | (((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board) or PWB) near29 (dielectric or non$4copper or (FR$3 near3 insulat$4))) and (((fill$4 or deposit$4 or embed$5) near26 (via or hole or through$4hole) near9 (capacit$4 or dielectric or ((capacit$4 or inorganic or resin) near9 (paste or material or composition or BaTiO$2 or (barium near2 titanate)))))) same contact$4 same bottom same top same electrode) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 30 | 3 | (((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board) or PWB) near29 (dielectric or non$4copper or (FR$3 near3 insulat$4))) and (((fill$4 or deposit$4 or embed$5) near26 (via or hole or through$4hole) near9 (capacit$4 or dielectric or ((capacit$4 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO$2 or (barium near2 titanate)))))) same contact$4 same bottom same top same electrode) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |

| | Hits | Search Text | DBs |
|---|---|---|---|
| 31 | 8 | (((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board) or PWB) near29 (dielectric or non$4copper or (FR$3 near3 insulat$4))) and (((fill$4 or deposit$4 or embed$5) near26 (via or hole or through$4hole) near9 (capacit$4 or dielectric or ((capacit$6 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO$2 or (barium near2 titanate))))) same bottom same top same electrode) and ((capacitor or ceramic or dielectric) same (contact$4 or juxtapos$3 or connect$4) same ((copper or Cu) near13 (layer or film or laminate or foil) near26 (upper or top or cover) near22 (lower or bottom or multilayer))) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |

| | Hits | Search Text | DBs |
|---|---|---|---|
| 32 | 8 | (((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board) or PWB) near29 (dielectric or non$4copper or (FR$3 near3 insulat$4) or FR$3)) and (((fill$4 or deposit$4 or embed$5) near26 (via or hole or through$4hole) near9 (capacit$4 or dielectric or ((capacit$6 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO$2 or (barium near2 titanate))))) same bottom same top same electrode) and ((capacitor or ceramic or dielectric) same (contact$4 or juxtapos$3 or connect$4 or attach$3) same ((copper or Cu) near13 (layer or film or laminate or foil) near26 (upper or top or cover) near22 (lower or bottom or multilayer))) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |